

# APTDF400KK120G

## Dual Common Cathode diodes Power Module

A1

A2

A2



#### Application

- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

#### Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
  - Very low stray inductance - Symmetrical design
- M5 power connectors
- High level of integration

#### Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

### Absolute maximum ratings

Symbol	Parameter			Max ratings	Unit		
V <sub>R</sub>	Maximum DC reverse Voltage			1200	V		
V <sub>RRM</sub>	Maximum Peak Repetitive Revers	e Voltage			1200	v	
т	Maximum Average Forward	Dute mult	- 500/	$T_C = 25^{\circ}C$	470		
$I_{F(AV)}$	Current	Duty cycle	e = 50%	$T_C = 60^{\circ}C$	400	Δ	
I <sub>F(RMS)</sub>	RMS Forward Current	Duty cycle = 50%		$T_C = 45^{\circ}C$	500	11	
I <sub>FSM</sub>	Non-Repetitive Forward Surge Cu	irrent	8.3ms	$T_C = 45^{\circ}C$	3000		

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

APTDF400KK120G - Rev 2 October, 2012



## All ratings (a) $T_j = 25^{\circ}C$ unless otherwise specified

### **Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit	
$\mathbf{V}_{\mathrm{F}}$	Diode Forward Voltage	$I_F = 400A$			2.4	3.0	
		$I_F = 600A$			2.7		V
		$I_{\rm F} = 400 {\rm A}$	$T_{j} = 125^{\circ}C$		1.8		
I <sub>RM</sub>	Maximum Reverse Leakage Current	$V_{R} = 1200V$ $\frac{T_{i} = 25^{\circ}C}{T_{j} = 125^{\circ}C}$	$T_i = 25^{\circ}C$			250	
			$T_{j} = 125^{\circ}C$			1000	μA
CT	Junction Capacitance	$V_{R} = 1200V$			440		pF

## **Dynamic Characteristics**

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit	
t <sub>rr</sub>	Reverse Recovery Time	$I_{F}=1A, V_{R}=30V$ di/dt = 400A/ $\mu$ s	$T_j = 25^{\circ}C$		45		ns
t <sub>rr</sub>	t <sub>rr</sub> Reverse Recovery Time		$T_j = 25^{\circ}C$		385		ns
۲r	Reverse Recovery Time		$T_{j} = 125^{\circ}C$		480		115
Q <sub>rr</sub>	Reverse Recovery Charge	$I_{\rm F} = 400 \text{A}$ $V_{\rm R} = 800 \text{V}$ $di/dt = 800 \text{A}/\mu \text{s}$	$T_j = 25^{\circ}C$		4.2		μC
Qrr	Reverse Recovery Charge		$T_{j} = 125^{\circ}C$		20.9		
I	Reverse Recovery Current		$T_j = 25^{\circ}C$		24		А
I <sub>RRM</sub>	Reverse Recovery Current		$T_{j} = 125^{\circ}C$		76		Л
t <sub>rr</sub>	Reverse Recovery Time	$I_{\rm F} = 400 {\rm A}$ $V_{\rm R} = 800 {\rm V}$ di/dt = 4000 {\rm A}/\mu {\rm s}			210		ns
Q <sub>rr</sub>	Reverse Recovery Charge		$T_j = 125^{\circ}C$		38		μC
I <sub>RRM</sub>	Reverse Recovery Current				280		А

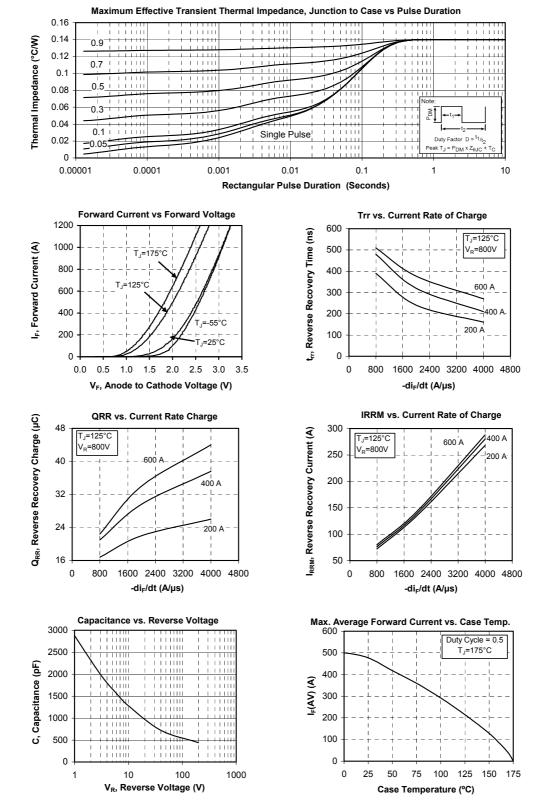
## Thermal and package characteristics

Symbol	Characteristic			Min	Тур	Max	Unit
R <sub>thJC</sub>	Junction to Case Thermal Resistance					0.14	°C/W
VISOL	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T <sub>J</sub>	Operating junction temperature range			-40		175	
T <sub>STG</sub>	Storage Temperature Range			-40 125 °C			
T <sub>C</sub>	Operating Case Temperature					100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
	ounting torque	For terminals	M5	2		3.5	19.111
Wt	Package Weight					300	g



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### **Typical Performance Curve**

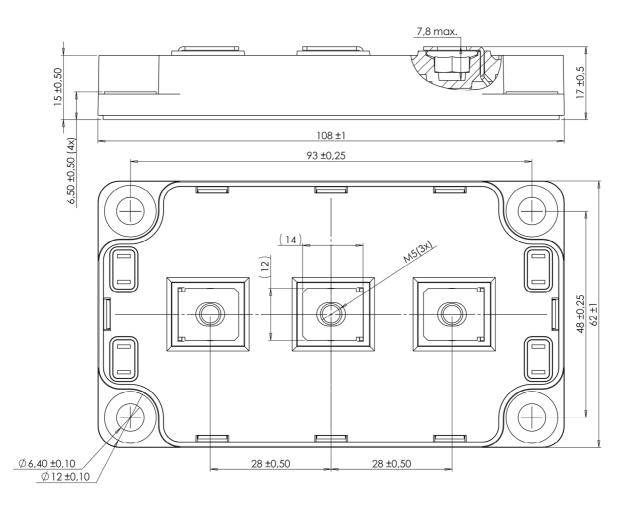


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### SP6 Package outline (dimensions in mm)





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